

# Silicon Diode

## **BYM63**

300V/2.4A

# DATASHEET

OEM – Philips

Source: Philips Databook 1999

## Ripple blocking diode

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## FEATURES

- Glass passivated
- High maximum operating temperature
- Low leakage current
- Excellent stability
- Guaranteed minimum turn-on time for absorbing forward current transients and oscillations
- Specially designed as rectifier in the auxiliary power supply in e.g. switched mode power supplies
- Available in ammo-pack.
- Also available with preformed leads for easy insertion.

## DESCRIPTION

Rugged glass SOD64 package, using a high temperature alloyed construction.

This package is hermetically sealed and fatigue free as coefficients of expansion of all used parts are matched.

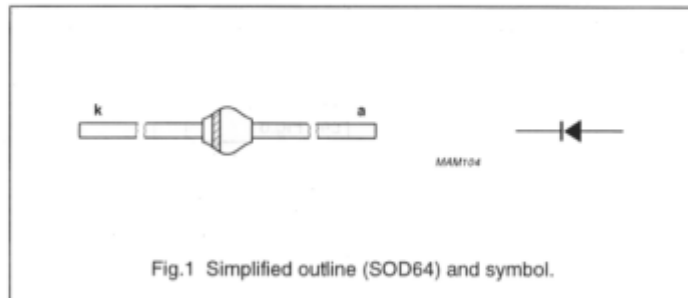


Fig.1 Simplified outline (SOD64) and symbol.

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{RRM}$	repetitive peak reverse voltage		–	300	V
$V_R$	continuous reverse voltage		–	300	V
$I_{F(AV)}$	average forward current	averaged over any 20 ms period; $T_{tp} = 55\text{ °C}$ ; lead length = 10 mm; see Fig.2; see also Fig.4	–	2.4	A
		averaged over any 20 ms period; $T_{amb} = 65\text{ °C}$ ; PCB mounting (Fig.8); see Fig.3; see also Fig.4	–	1.0	A
$I_{FRM}$	repetitive peak forward current	$T_{tp} = 55\text{ °C}$	–	21	A
		$T_{amb} = 65\text{ °C}$	–	8.5	A
$I_{FSM}$	non-repetitive peak forward current	$t = 10\text{ ms}$ half sine wave; $T_j = T_{jmax}$ prior to surge; $V_R = V_{RRMmax}$	–	45	A
$T_{stg}$	storage temperature		–65	+175	°C
$T_j$	junction temperature		–65	+175	°C

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**ELECTRICAL CHARACTERISTICS** $T_j = 25\text{ °C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_F$	forward voltage	$I_F = 2\text{ A}$ ; $T_j = T_{j\text{max}}$ ; see Fig.5	–	–	1.34	V
		$I_F = 2\text{ A}$ ; see Fig.5	–	–	2.30	V
$I_R$	reverse current	$V_R = V_{RRM\text{max}}$ ; see Fig.6	–	–	10	$\mu\text{A}$
		$V_R = V_{RRM\text{max}}$ ; $T_j = 165\text{ °C}$ ; see Fig.6	–	–	150	$\mu\text{A}$
$t_{fr}$	forward recovery time	when switched to $I_F = 5\text{ A}$ in 50 ns; see Fig.9	–	–	1.5	$\mu\text{s}$
$t_{on}$	turn-on time	when switched from $V_F = 0\text{ V}$ to $V_F = 3\text{ V}$ ; measured between 10% and 90% of $I_{F\text{max}}$ ; see Fig.11	400	–	–	ns
$t_{rr}$	reverse recovery time	when switched from $I_F = 0.5\text{ A}$ to $I_R = 1\text{ A}$ ; measured at $I_R = 0.25\text{ A}$ ; see Fig.11	–	–	150	ns
$C_d$	diode capacitance	$f = 1\text{ MHz}$ ; $V_R = 0\text{ V}$ ; see Fig.7	–	65	–	pF

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j\text{-tp}}$	thermal resistance from junction to tie-point	lead length = 10 mm	25	K/W
$R_{th\ j\text{-a}}$	thermal resistance from junction to ambient	note 1	75	K/W

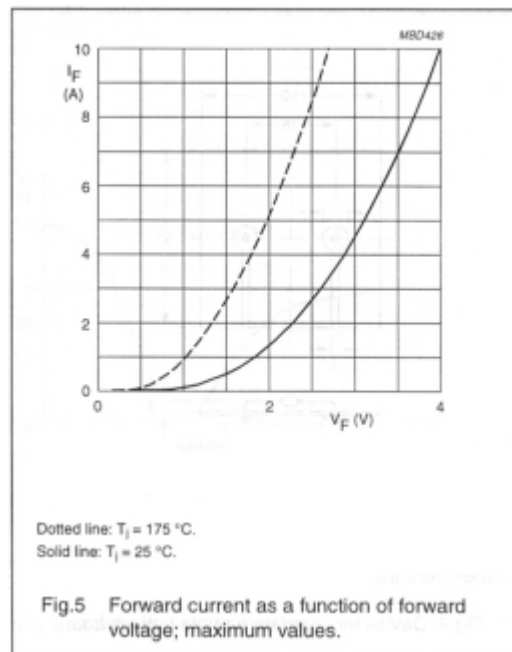
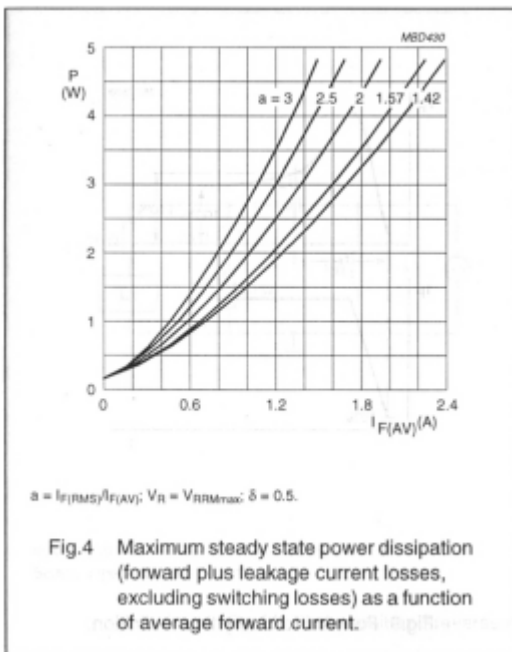
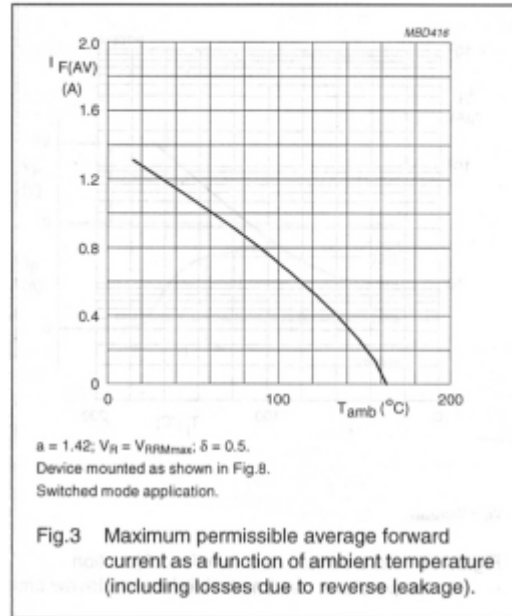
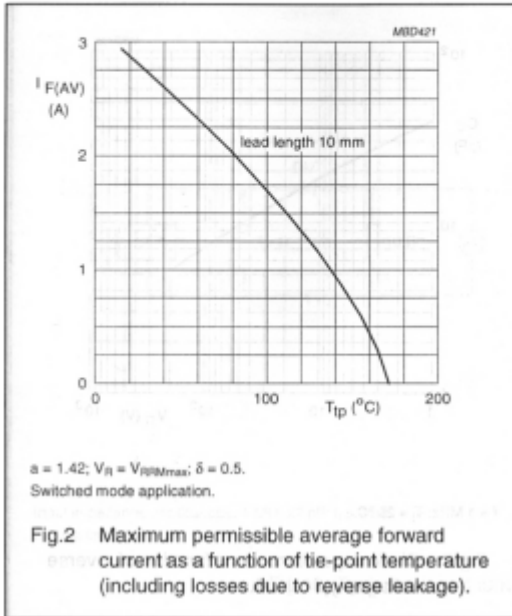
**Note**

1. Device mounted on an epoxy-glass printed-circuit board, 1.5 mm thick; thickness of Cu-layer  $\geq 40\text{ }\mu\text{m}$ , see Fig.8. For more information please refer to the 'General Part of Handbook SC01.'

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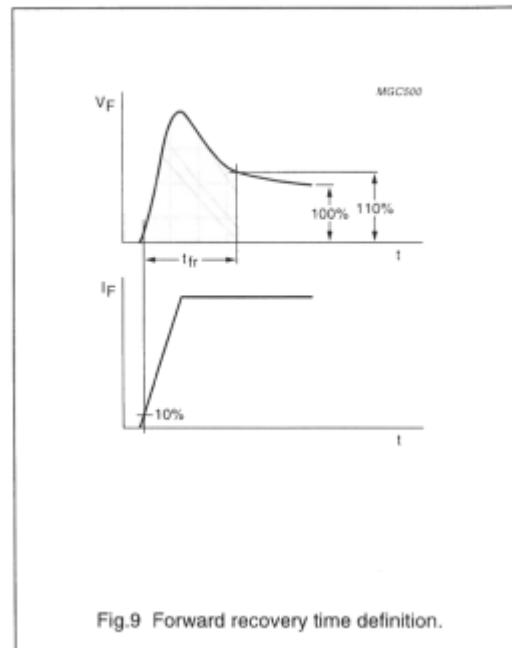
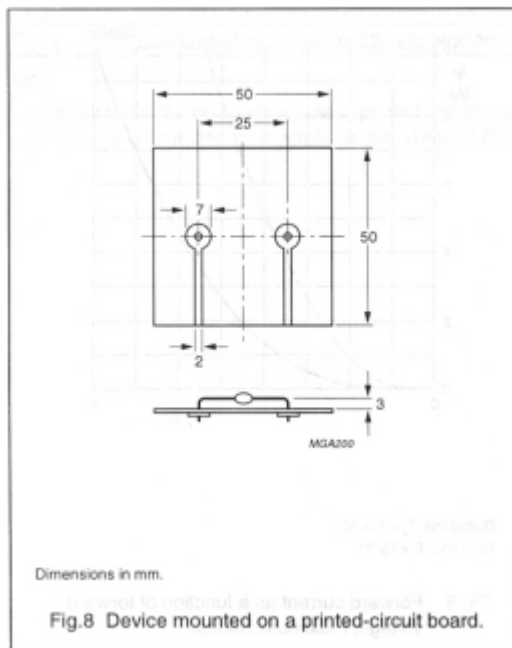
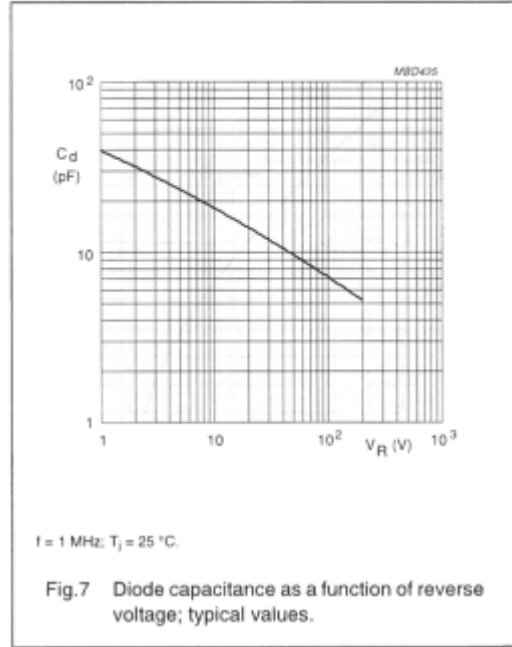
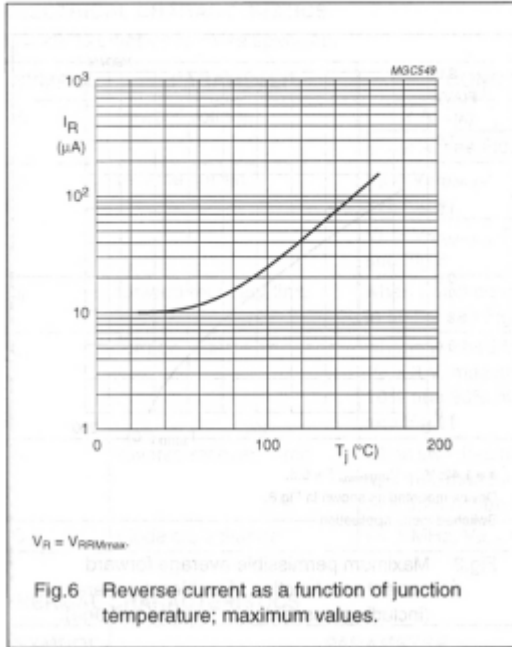
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GRAPHICAL DATA



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